



Material Content Data Sheet



Halogen-Free

Sales Product Name	ISC0804NLS	Issued	23. June 2021
MA#	MA005431947		
Package	PG-TDSON-8-51	Weight*	101.66 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.510	0.50	0.50	5012	5012
leadframe	inorganic material	phosphorus	7723-14-0	0.014	0.01		134	
	non noble metal	zinc	7440-66-6	0.055	0.05		536	
	non noble metal	iron	7439-89-6	1.090	1.07		10725	
	non noble metal	copper	7440-50-8	44.271	43.57	44.70	435476	446871
wire	noble metal	gold	7440-57-5	0.035	0.03	0.03	340	340
encapsulation	organic material	carbon black	1333-86-4	0.088	0.09		868	
	plastics	epoxy resin	-	4.061	3.99		39949	
	inorganic material	silicondioxide	60676-86-0	39.994	39.34	43.42	393406	434223
leadfinish	non noble metal	tin	7440-31-5	1.264	1.24	1.24	12431	12431
plating	noble metal	silver	7440-22-4	0.029	0.03	0.03	285	285
solder	noble metal	silver	7440-22-4	0.019	0.02		187	
	non noble metal	tin	7440-31-5	0.038	0.04		373	
	non noble metal	lead	7439-92-1	0.702	0.69	0.75	6908	7468
heat sink clip	inorganic material	phosphorus	7723-14-0	0.003			28	
	non noble metal	zinc	7440-66-6	0.011	0.01		112	
	non noble metal	iron	7439-89-6	0.228	0.22		2241	
	non noble metal	copper	7440-50-8	9.250	9.10	9.33	90989	93370
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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